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Product Change Notification - GBNG-05QUVX037 [\(Convert To PDF\)](#)

Date:

09 Aug 2018

Product Category:

8-bit Microcontrollers

Affected CPNs:

Notification subject:

CCB 3496 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of the 35.4K, 35.5K and 35.9K wafer technologies available in 100L TQFP (14x14x1.0mm) package.

Notification text:
PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Atmel products of the 35.4K, 35.5K and 35.9K wafer technologies available in 100L TQFP (14x14x1.0mm) package.

Pre Change:

Assembled in ASE using Au, PdCu or CuPdAu wire, CRM-1076WA die attach, G631H mold compound and C7025 lead frame material with MSL 3 classification or assembled in LPI using Au or CuPdAu wire and CRM-1033BF die attach material with MSL 3 classification.

Post Change:

Assembled in ASE using Au, PdCu or CuPdAu wire, CRM-1076WA die attach, G631H mold compound and C7025 lead frame material with MSL 3 classification or assembled in LPI using Au or CuPdAu wire and CRM-1033BF die attach material with MSL 3 classification.or assembled in MMT using Au wire, 3280 die attach, G700 mold compound and C194 lead frame material with MSL 1 or MSL 2 classification.

Pre and Post Change Summary:

	Pre Change						Post Change					
Assembly Site	ASE Inc. Taiwan (ASE)			Lingsen Precision Industries, LTD. (LPI)			ASE Inc. Taiwan (ASE)			Lingsen Precision Industries, LTD. (LPI)		Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	PdCu	CuPdAu	Au	CuPdAu	Au	PdCu	CuPdAu	Au	CuPdAu	Au	

Die attach material	CRM-1076WA	CRM-1033BF	CRM-1076WA	CRM-1033BF	3280
Molding compound material	G631H	G700	G631H	G700	G700
Lead frame material	C7025	C194	C7025	C194	C194
MSL Classification	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1 or MSL 2

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To Improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					-->	November 2018				
	31	32	33	34	35		44	45	46	47	48
Workweek											
Initial PCN Issue Date		X									
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 09, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-05QUVX037_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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